PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2983757

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HONG HE	08/11/2014
JONG-KAE FWU	08/07/2014
SEUNGHEE HAN	08/11/2014
GANG XIONG	08/07/2014

RECEIVING PARTY DATA

Name:	INTEL IP CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14318143

CORRESPONDENCE DATA

Fax Number: (612)677-3572

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6122369997

Email: stoel@CPAGLOBAL.COM

Correspondent Name: STOEL RIVES, LLP. Address Line 1: C/O CPA GLOBAL Address Line 2: P.O. BOX 52050

Address Line 4: MINNEAPOLIS, MINNESOTA 55402

ATTORNEY DOCKET NUMBER:	P66312
NAME OF SUBMITTER:	KEVIN AUSTAD
SIGNATURE:	/Kevin Austad/
DATE SIGNED:	08/15/2014

Total Attachments: 8

source=P66312 ASSN#page1.tif source=P66312_ASSN#page2.tif

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

HONG HE; JONG-KAE FWU; SEUNGHEE HAN; GANG XIONG

hereby sell, assign, and transfer to:

Intel IP Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

HARQ TIMELINES FOR TDD-FDD CARRIER AGGREGATION

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on	<u>June 27, 2014</u> as	3		
US		Application Number	14/318,143	and
COUNTRY or Inte	ernational Office	• •	•	•

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and

the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Hong He	2014-08-11
Hong He	Date signed
Jong-Kae Fwu	Date signed
Seunghee Han	Date signed
Gang Xiong	Date signed

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Hong He	Date signed
John Ja	08/07/2014
Jong-Kae Fwu	Date signed
Seunghee Han	Date signed
Gang Xiong	Date signed

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Hong He	Date signed
Jong-Kae Fwu	Date signed
	08/11/2014
Seunghee Han	Date signed
Gang Xiong	Date signed

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Hong He	Date signed	
Jong-Kae Fwu	Date signed	
Seunghee Han	Date signed	
Samuel Comment of the	08/07/2019	
Gang Xiông	Date signed	